

Electrical and Optical Characteristics (Ta = 25°C)

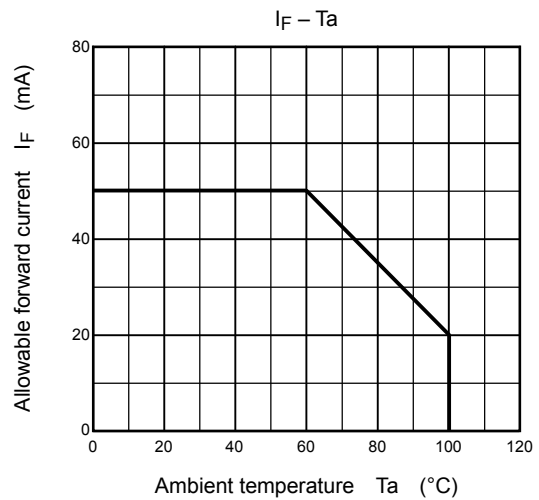
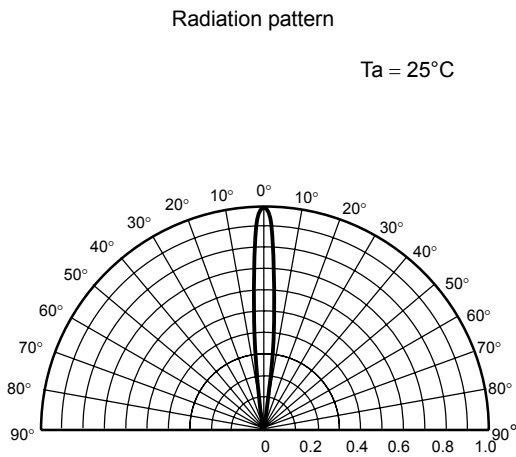
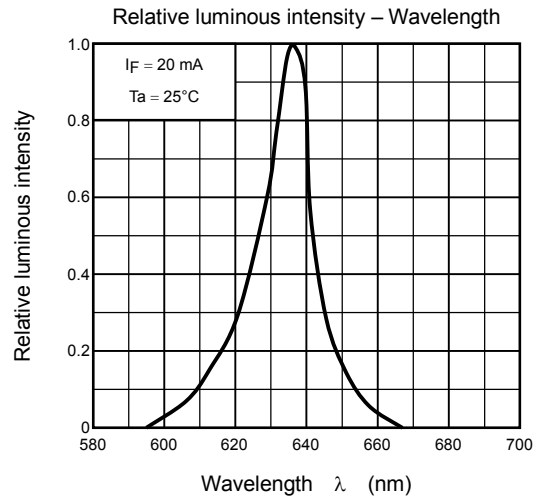
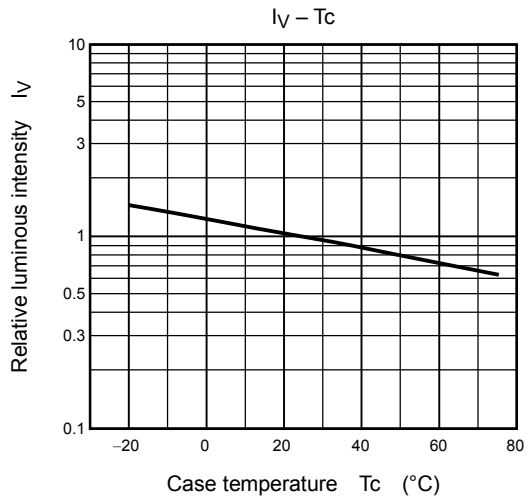
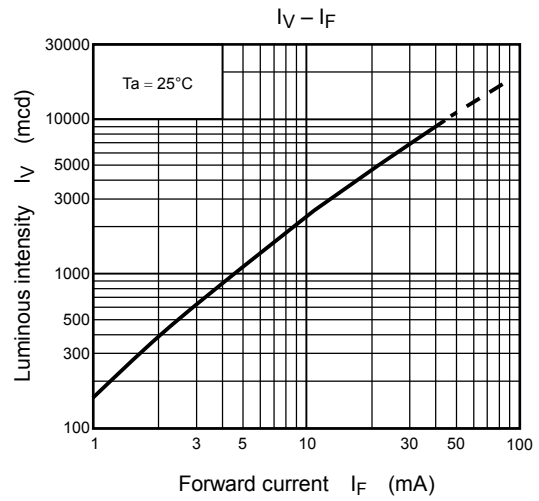
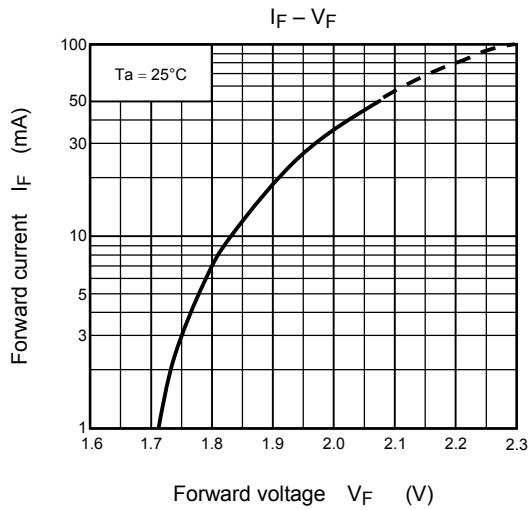
Product Name	Typ. Emission Wavelength				Luminous Intensity I _V			Forward Voltage V _F			Reverse Current I _R	
	λ _d	λ _p	Δλ	I _F	Min	Typ.	I _F	Typ.	Max	I _F	Max	V _R
TLRMH38TP	626	(636)	13	20	1530	4800	20	1.9	2.4	20	50	4
TLSH38TP	613	(623)	13	20	2720	6500	20	2.0	2.4	20	50	4
TLOH38TP	605	(612)	13	20	2720	7500	20	2.0	2.4	20	50	4
TLYH38TP	587	(590)	13	20	2720	7000	20	2.0	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

Precautions

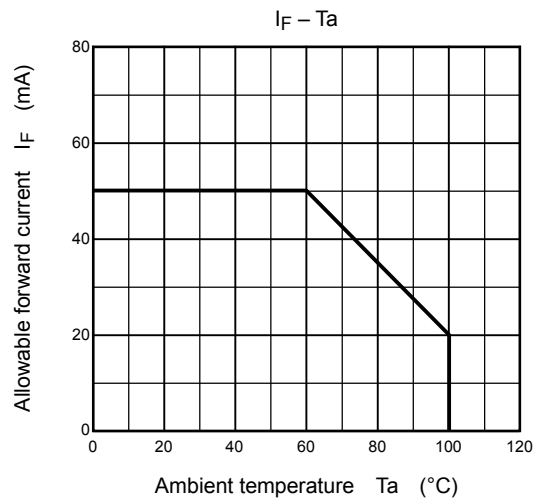
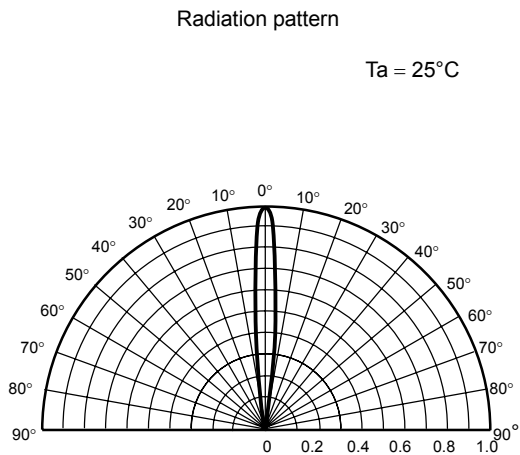
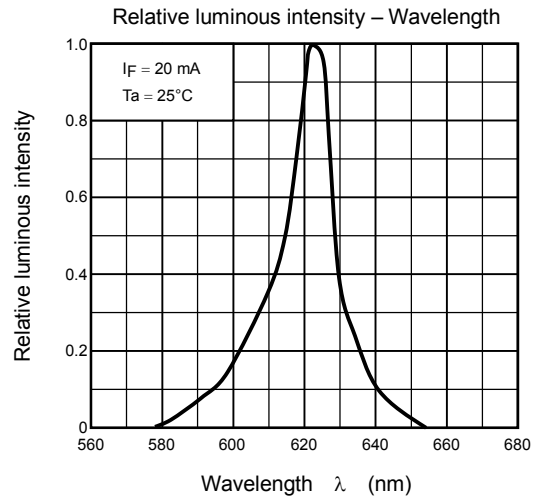
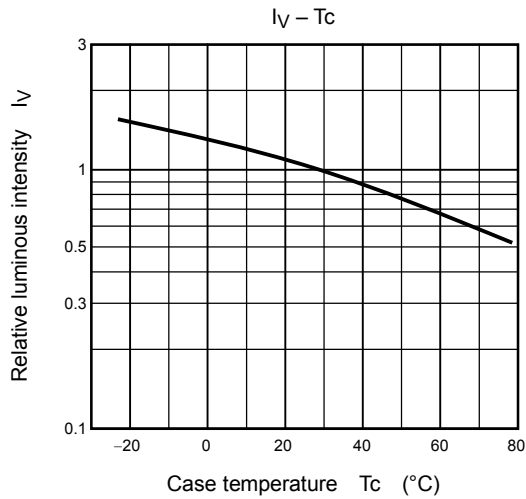
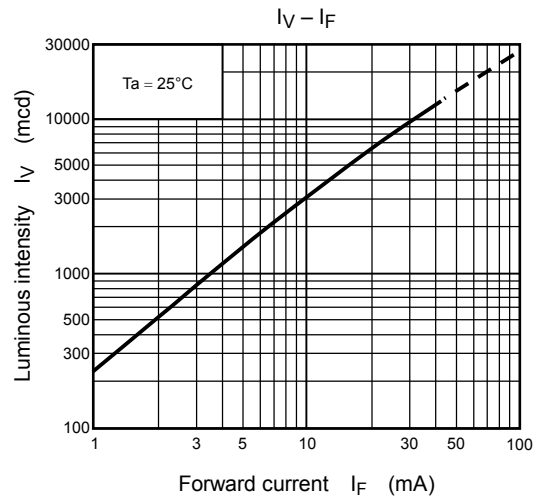
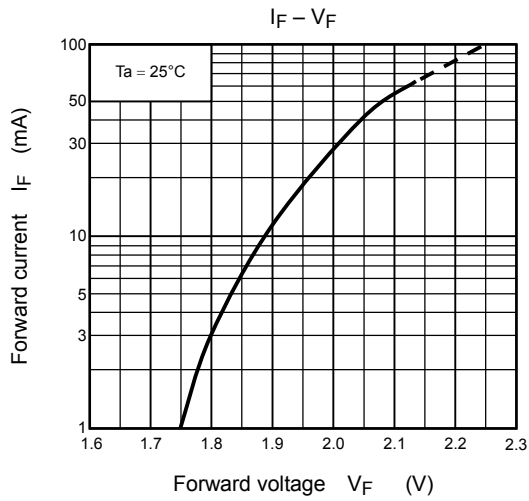
Please be careful of the following:

- Soldering temperature: 260°C max, soldering time: 3 s max
(soldering portion of lead: up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

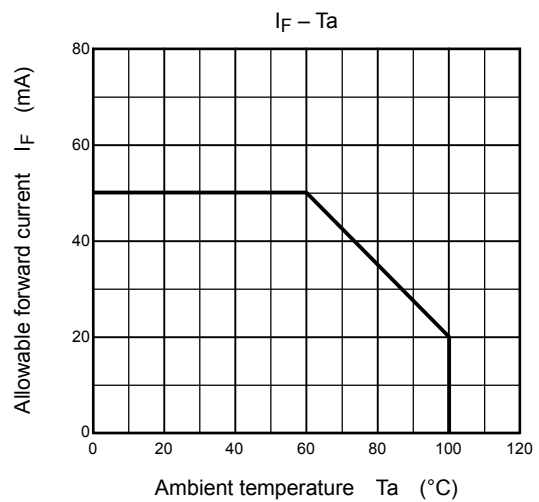
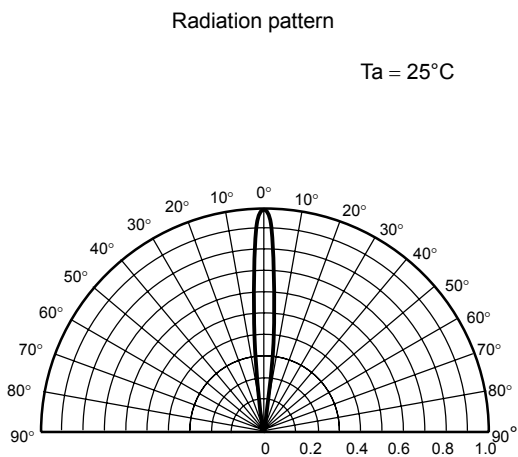
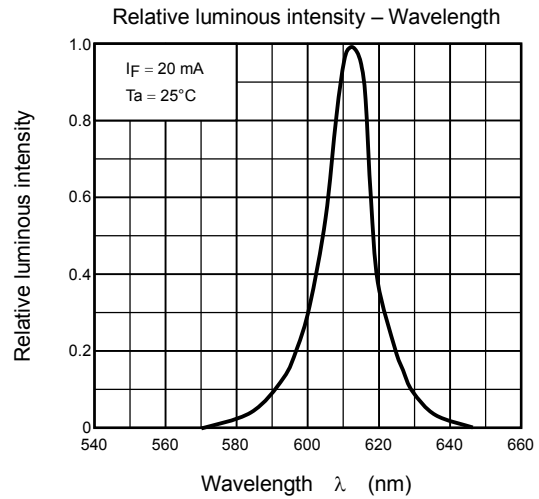
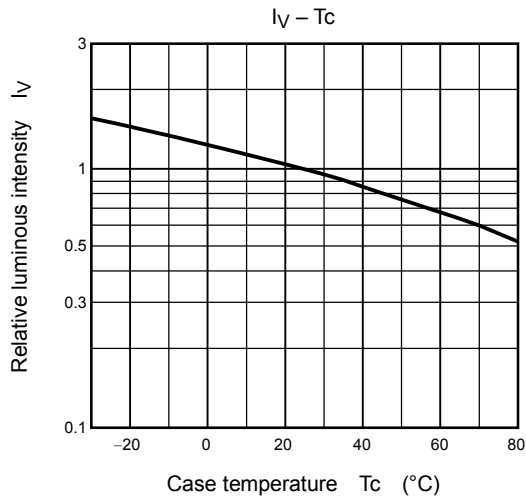
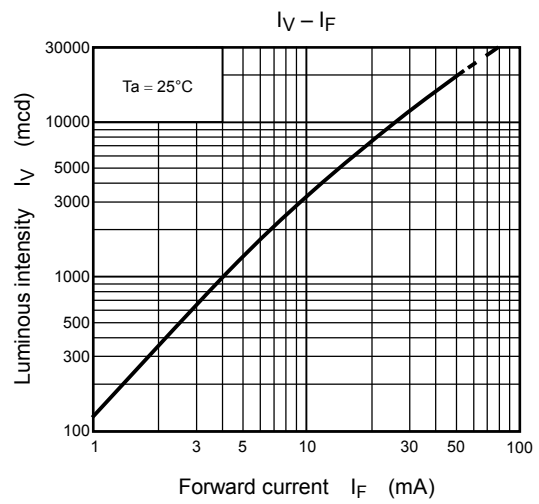
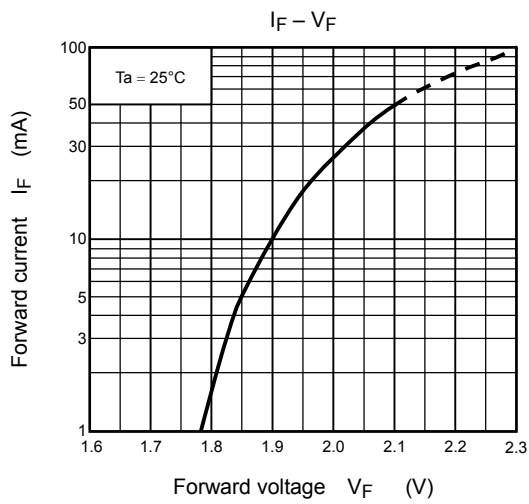
TLRMH38TP



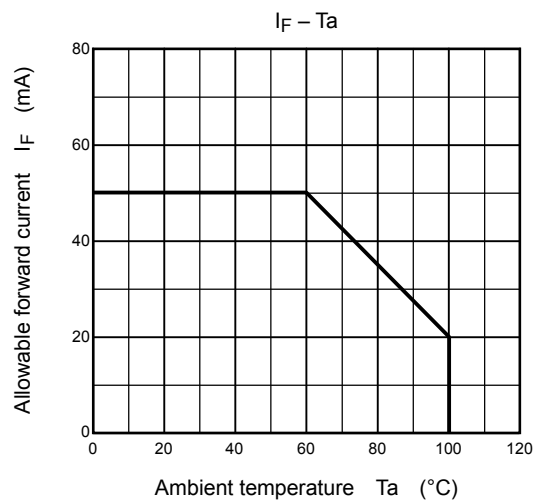
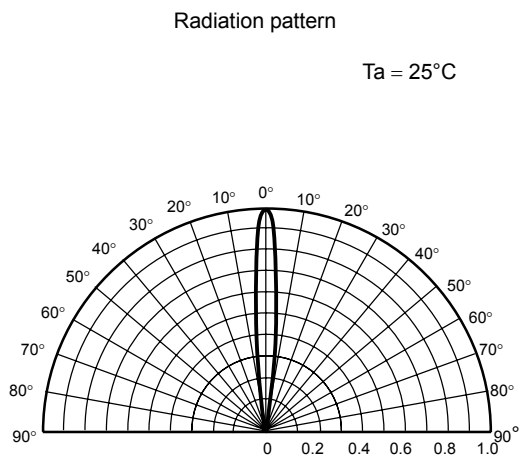
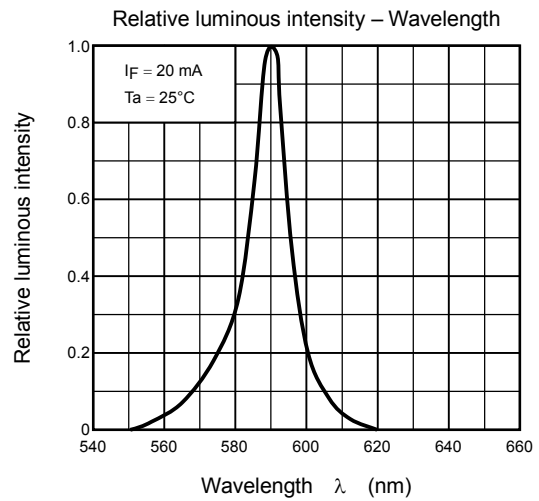
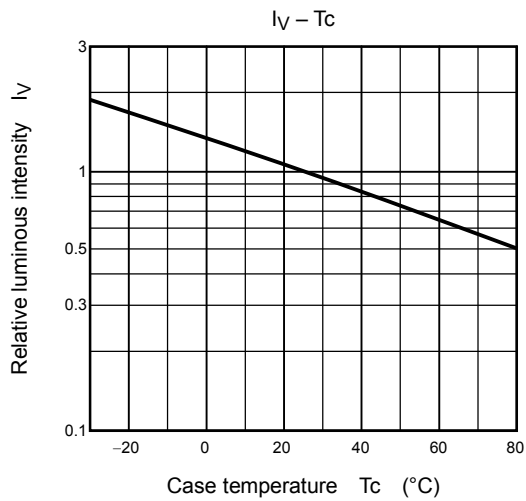
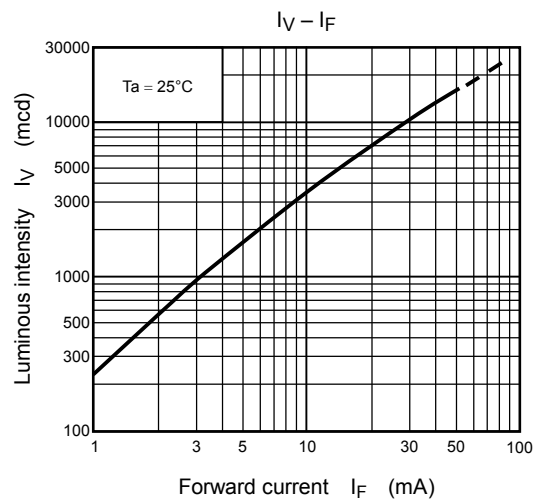
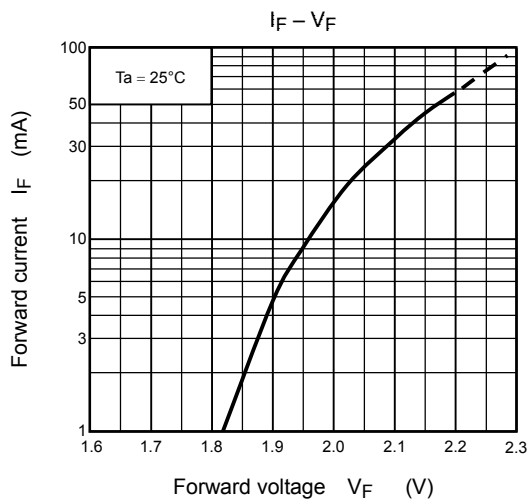
TLSH38TP



TLOH38TP



TLYH38TP



RESTRICTIONS ON PRODUCT USE

000707EAC

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